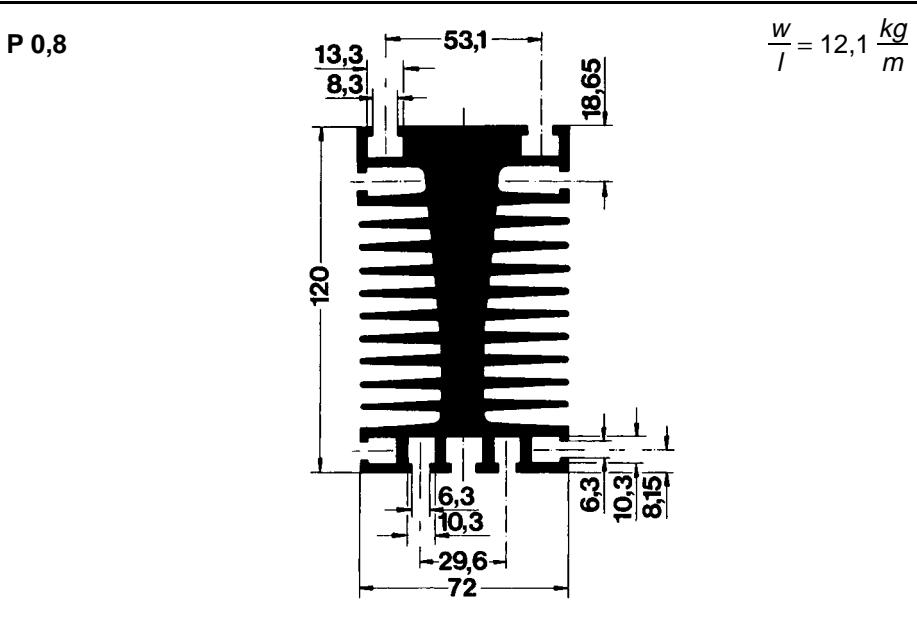
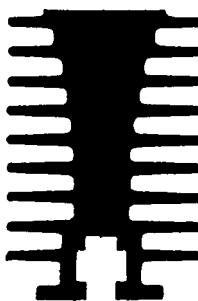
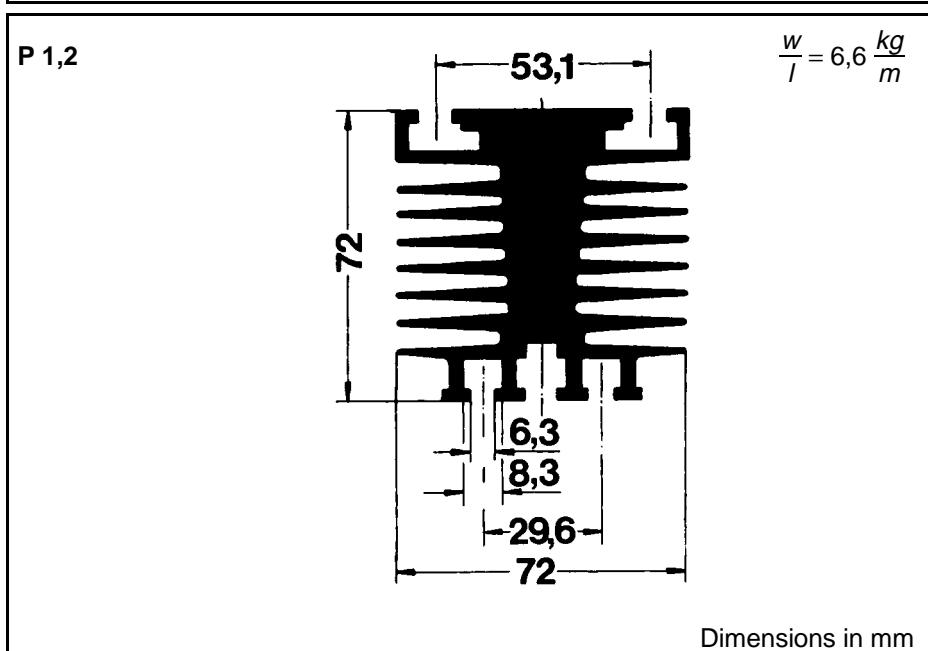


[back](#)[zurück](#)

Standard lengths <sup>1)</sup>	n	$R_{thha}$ <sup>2)</sup> natural cooling °C/W	$R_{thha}$ <sup>2)</sup> $V_{air} =$ 5m/s °C/W	w
				kg
P 0,8/120 P 0,8/150	1 1	0,62 (100 W) 0,57 (100 W)	0,13 0,10	1,45 1,8
P 1,2/100 P 1,2/200	1 2	1,1 (50 W) 1,0 (50 W)		0,66 1,3
C 3/120	1	2,2 (20 W)	0,5	0,37

**Heatsinks****P 0,8****P 1,2****C 3****Features**

- Intended for stud mounted devices
- Available in various lengths
- Several devices can be mounted on a single heatsink

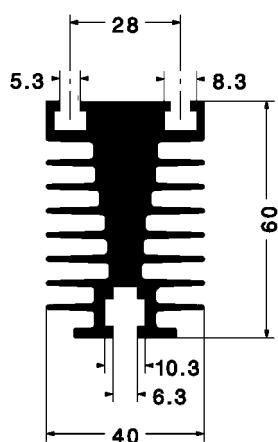


Dimensions in mm

<sup>1)</sup> Non-standard lengths available on request<sup>2)</sup> At the given power dissipation per semiconductor component

**C 3**

$$\frac{w}{l} = 3,3 \frac{\text{kg}}{\text{m}}$$



Dimensions in mm

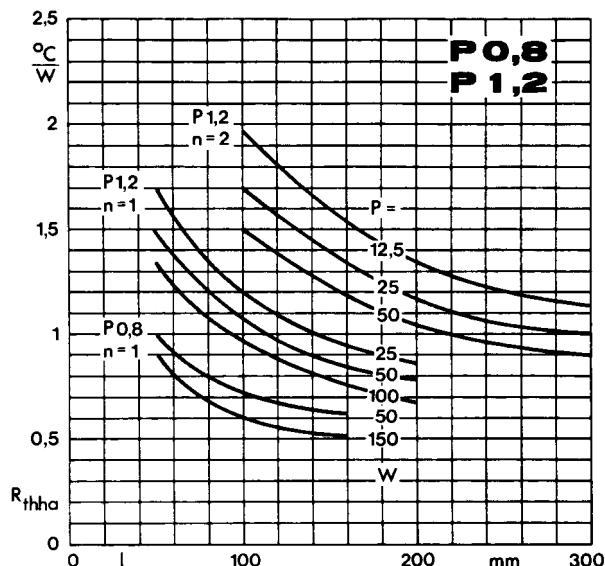


Fig. 2 a Thermal resistance per component vs. length

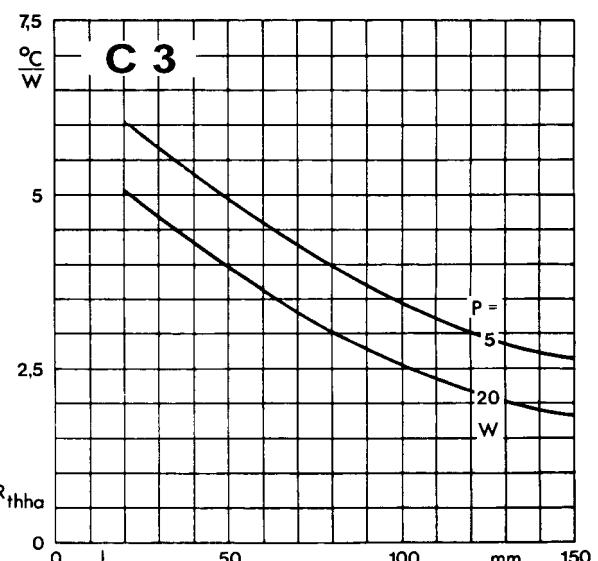


Fig. 2 b Thermal resistance per component vs. length

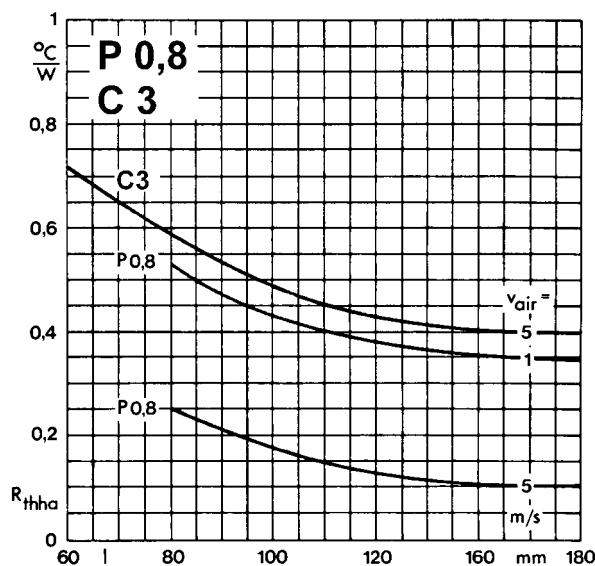
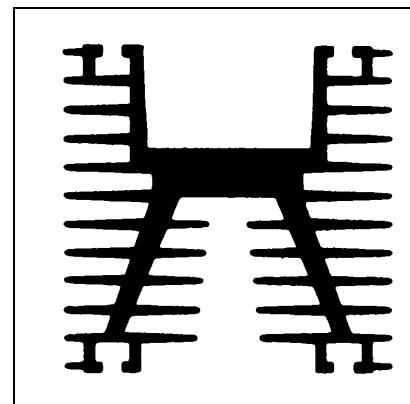


Fig. 6 Total thermal resistance vs. length

Standard lengths <sup>1)</sup>	$R_{thha}$ <sup>2)</sup> natural cooling °C/W	$R_{thha}$ <sup>3)</sup> forced air cooling °C/W	w kg
<b>P 1/75 - M 8</b> <b>P 1/75 - M12</b>	1,0 ( 50 W) 0,85 ( 70 W)	0,45 0,33	0,82
<b>P 1/120 - M 8</b> <b>P 1/120 - M12</b>	0,75 (100 W) 0,60 (120 W)	0,40 0,28	1,3
<b>P 1/200 - M16 x 1,5</b> <b>P 1/200 - M24 x 1,5</b>	0,43 (150 W) 0,40 (200 W)	0,17 0,15	2,2
<b>P 1/120 - 45 mm</b> <b>P 1/120 - 49 mm<sup>4)</sup></b> <b>P 1/120 - 49 mm<sup>5)</sup></b> <b>P 1/120 - 60 mm</b>	0,70 ( 70 W) 0,70 ( 70 W) 0,60 (100 W) 0,60 (100 W)	0,25 0,25 0,20 0,21	1,3
<b>P 1/200 - 49 mm<sup>5)</sup></b> <b>P 1/200 - 60 mm</b>	0,47 (130 W) 0,47 (130 W)	0,17 0,18	2,2

## Heatsinks

### P 1



#### Features

- Intended for discrete components and bridge rectifiers
- Available in various lengths
- Several devices can be mounted on a single heatsink
- Mounting channels are provided for additional accessories

<sup>1)</sup> Non standard lengths available on request

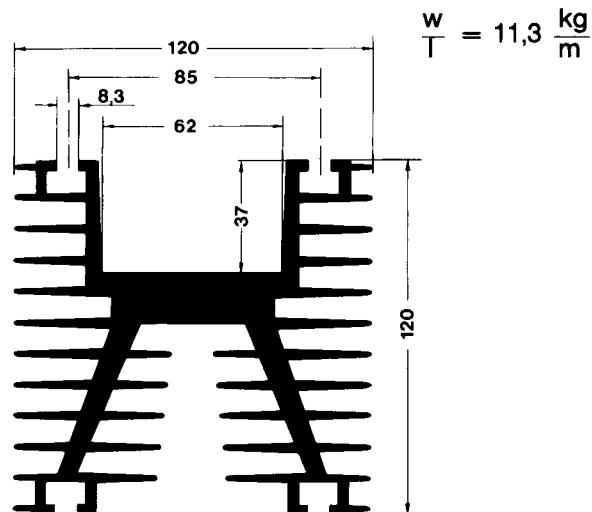
<sup>2)</sup> At the given power dissipation per semiconductor component

<sup>3)</sup> With fan type

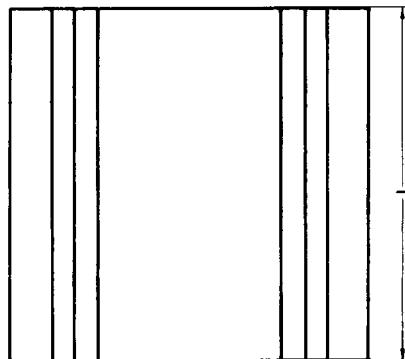
<sup>4)</sup> SEMIPONT 1

<sup>5)</sup> SEMIPONT 2

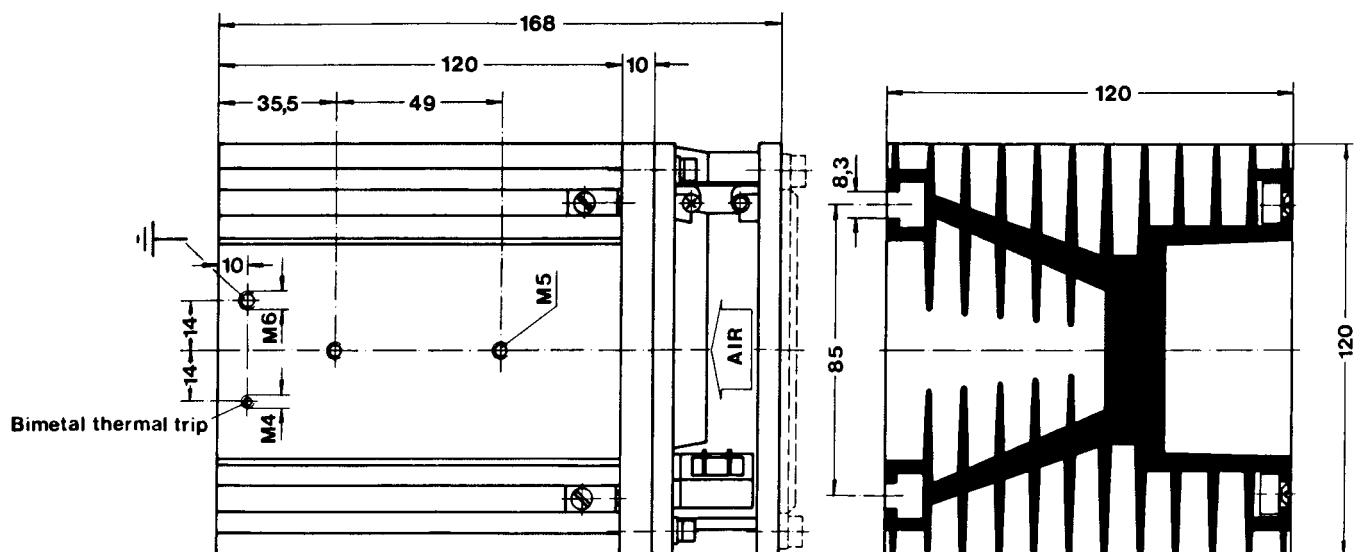
**P1**



P 1/120 : l = 120 mm  
P 1/200 : l = 200 mm



Example: P 1/120 F for SEMIPONTs



Dimensions in mm

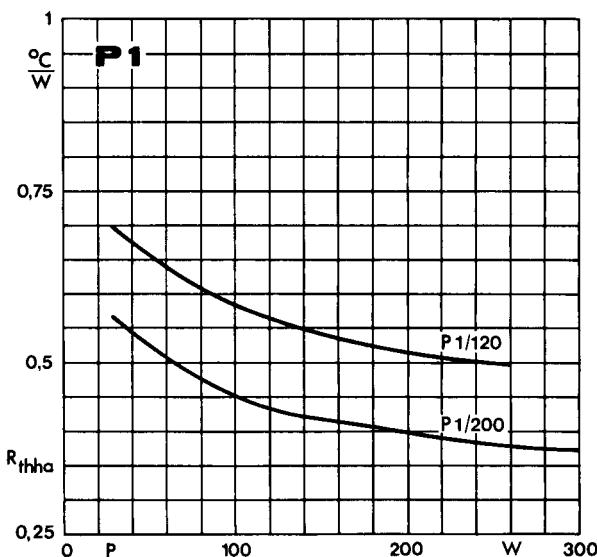


Fig. 1 Thermal resistance vs. dissipated power

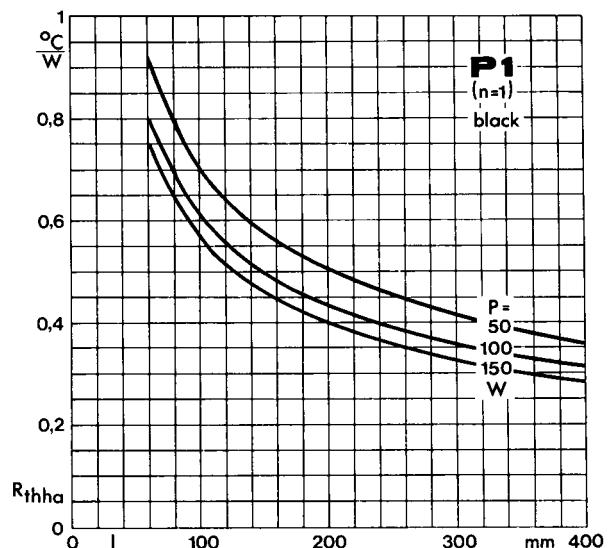


Fig. 2 a Thermal resistance per component vs. lenght

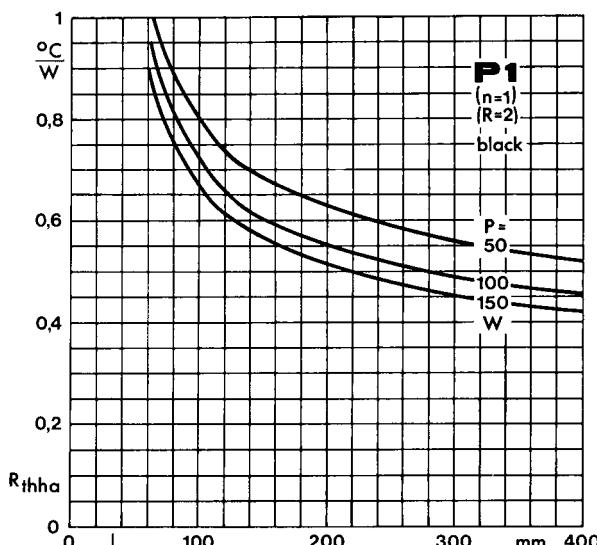


Fig. 2 b Thermal resistance per component vs. length

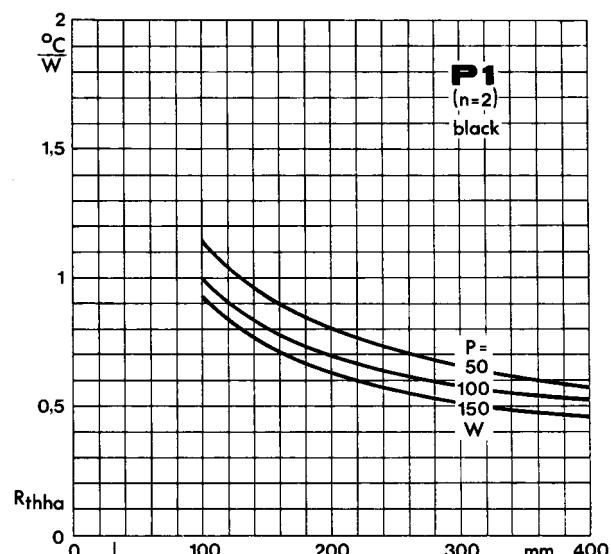


Fig. 2 c Thermal resistance per component vs. length

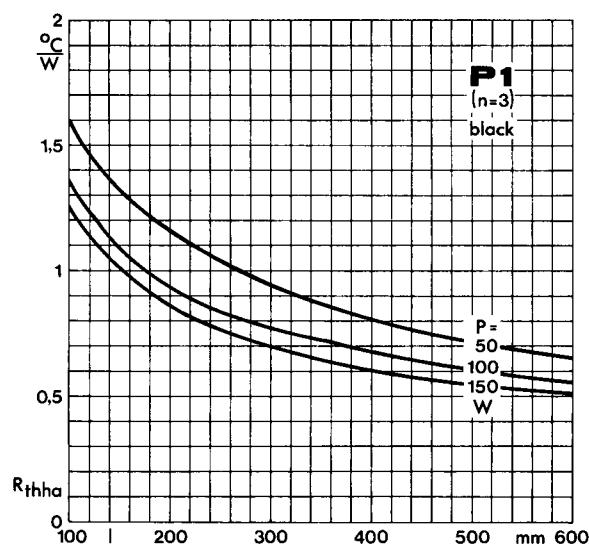


Fig. 2 d Thermal resistance per component vs. length

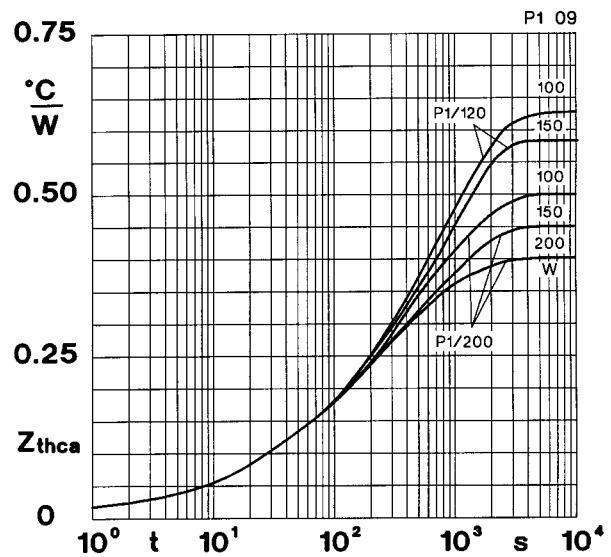


Fig. 9 Transient thermal impedance vs. time